

Alloy	Sn / Cu0.7
Melting Point	Approx. 227~228°C
Flux Content	%1- % 3

- + Zero halogen
- + No corrosion
- + No Clean
- + Provides excellent wetting with flux formula
- + Soldering is easy

<b>Technical Specification</b>	
Appearance	Bright and shiny surface finishes.
Gravity	7.3
Spread ability	>%75
Packaging	0,5kg
Copper Mirror Test	Pass
Copper plate corrosion	Pass
S.I.R Test	PASS 1×1010 Ω up
Electrochemical migration test	PASS 1×1010 Ω up